SP120N

No-Flow Prepreg

FEATURES

- High peel strength
- Minimal resin flow, flexible
- Excellent process ability, punching compatible
- Excellent thermal reliability and electrical properties

APPLICATIONS

Suitable for bonding used in die cavity board and multilayer rigid-flex PCB application.

GENERAL PROPERTIES

Test Items	Test Method	Test Condition	Unit	Typical Value
Tg	IPC-TM-650 2.4.25D	DSC	℃	125
Td	IPC-TM-650 2.4.24.6	TGA (5% W.L)	℃	315
T288	IPC-TM-650 2.4.24.1	TMA	min	5
T260	IPC-TM-650 2.4.24.1	TMA	min	30
Thermal Stress	IPC-TM-650 2.4.13.1	288℃, solder dip	s	>100
Volume Resistivity	IPC-TM-650 2.5.17.1	C-96/35/90	MΩ-cm	5.0×10^{8}
Surface Resistivity	IPC-TM-650 2.5.17.1	C-96/35/90	MΩ	5.0×10^{7}
Peel Strength (1oz)	IPC-TM-650 2.4.8	288℃/10s	N/mm [lb/in]	2.0 [11.43]
Water Absorption	IPC-TM-650 2.6.2.1	D-24/23	%	0.15
Flammability	UL94	C-48/23/50	Rating	V-0

Remarks: All the typical value listed above is for your reference only, please turn to Shengyi Technology Co., Ltd for detailed information, and all rights from this data sheet are reserved by Shengyi Technology Co., Ltd.

PREPREG PARAMENTERS

Glass fabric	Resin content (%)	Cured thickness (mm)	Standard roll size
1080	64	0.080	0.25m×100m，0.50m×100m 1.265m×150m
106	72	0.050	

Remarks: 3 months when stored at <23℃ and <50%RH, 6 months when stored at <5℃.

HOT PRESSING CYCLE

- Heat up rate: 3.0-5.0℃/min (70-130℃)
- Curing time: >30min (170~180℃)
- The heat up rate is for your reference only; please turn to Shengyi Technology Co., Ltd. for detailed information.